

### General Description

The CMP50N06 is extremely high-density N-channel MOSFET, which provides the best R<sub>DS(on)</sub> and gate charge for the synchronous buck converter applications.

### Features

- 50A,60V.RDS(ON)=0.018Ω @VGS=10V
- Fast Switching
- N-channel-Enhancement mode
- Low Threshold Drive
- 100% Avalanche Tested

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1</sup>	50	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current <sup>1</sup>	30	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	150	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	160	mJ
I <sub>AS</sub>	Avalanche Current	30	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	90	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	65	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case	---	1.4	°C/W

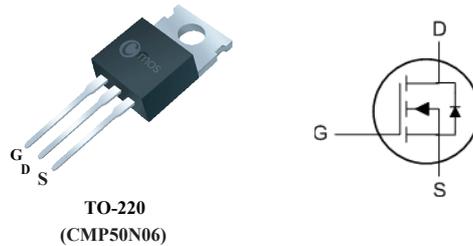
### Product Summary

BVDSS	R <sub>DS(on)</sub>	I <sub>D</sub>
60V	18mΩ	50A

### Applications

- Power Supplies
- DC-DC & DC-AC Converters
- Motor Control, Audio Amplifiers
- High Current, High Speed Switching
- Solenoid And Relay Drivers

### TO-220 Pin Configuration



**Electrical Characteristics (T<sub>J</sub>=25°C , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A	---	16	18	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	---	3	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V , V <sub>GS</sub> =0V	---	---	1	uA
		V <sub>DS</sub> =60V , V <sub>GS</sub> =0V , T <sub>C</sub> =125°C	---	---	10	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A	---	15	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	2	---	Ω
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =50 A V <sub>DS</sub> =48 V V <sub>GS</sub> =5 V	---	30	44	nC
Q <sub>gs</sub>	Gate-Source Charge		---	8.6	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	16	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =30 V I <sub>D</sub> =22.5A R <sub>G</sub> =6.9Ω V <sub>GS</sub> =10V	---	17	---	ns
T <sub>r</sub>	Rise Time		---	159	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	68	---	
T <sub>f</sub>	Fall Time		---	89	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz	---	1500	---	pF
C <sub>oss</sub>	Output Capacitance		---	580	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	120	---	

**Diode Characteristics**

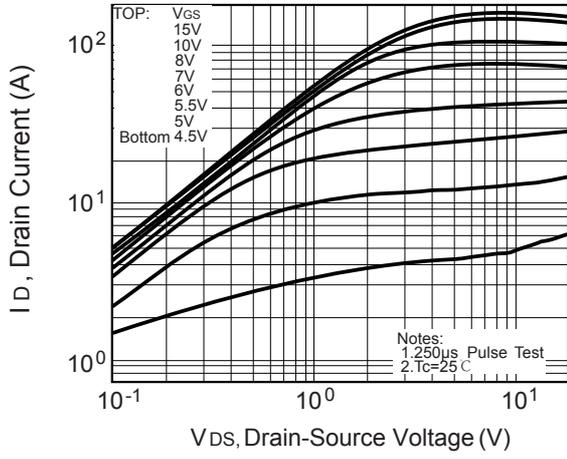
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	50	A
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>		---	---	150	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =45 A , T <sub>J</sub> =25°C	---	---	1.32	V

Note :

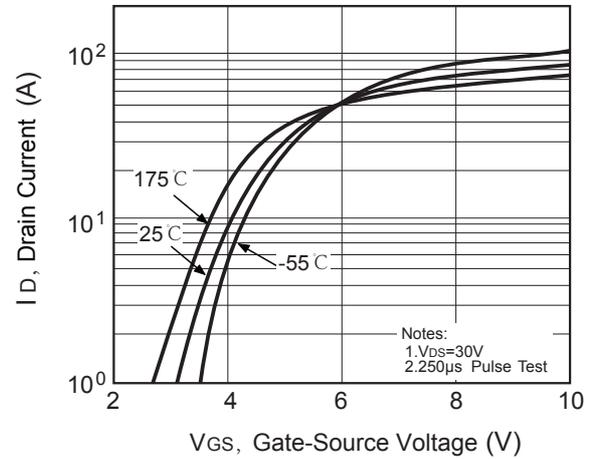
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=30A.

This product has been designed and qualified for the consumer market.  
Cmos assumes no liability for customers' product design or applications.  
Cmos reserves the right to improve product design ,functions and reliability without notice.

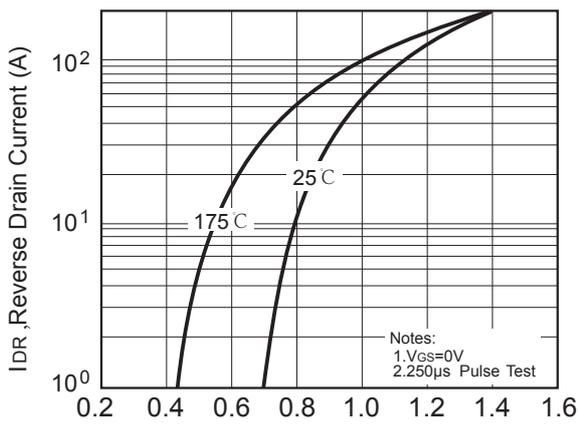
Typical Characteristics



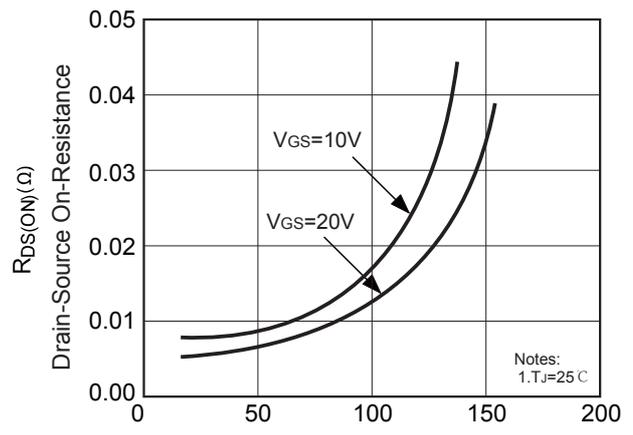
Output Characteristics



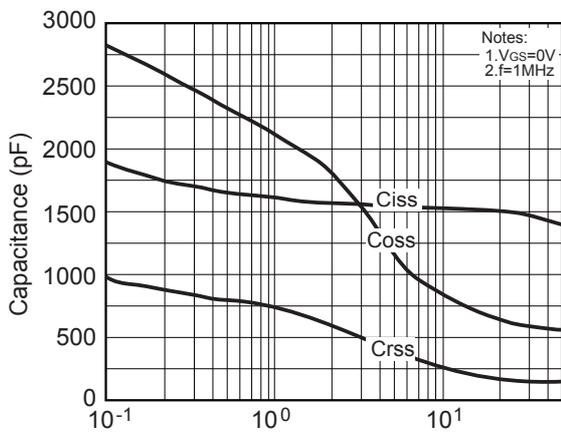
Transfer characteristics



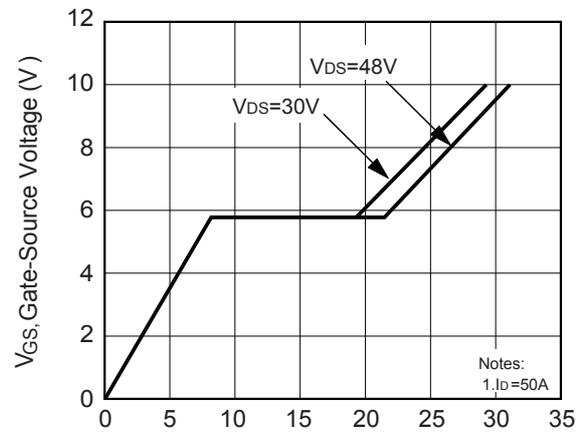
Body Diode Forward Voltage Variation vs. Source Current and Temperature



On-Resistance Variation vs. Drain Current and Gate Voltage

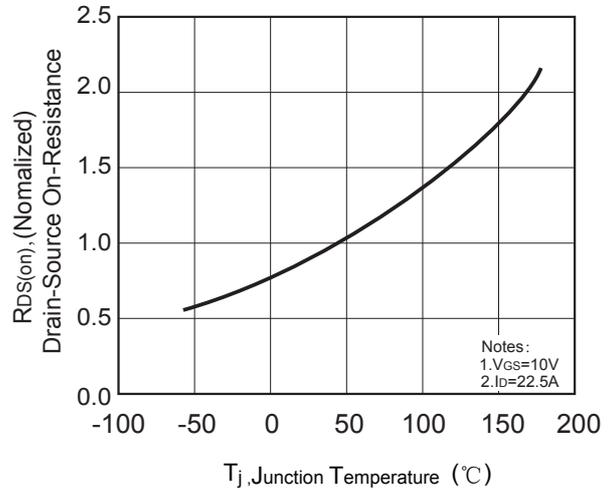
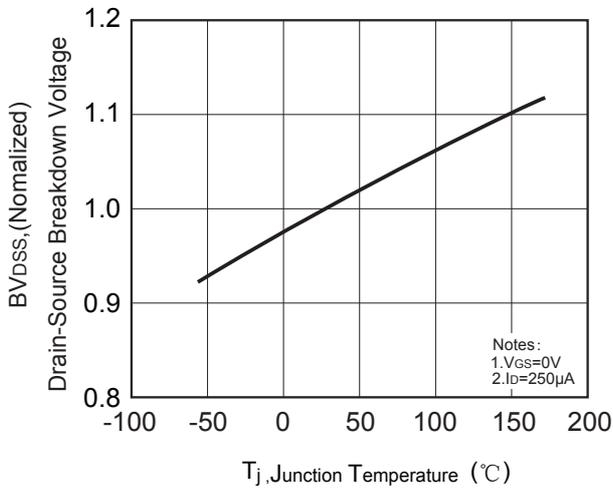


Capacitance Characteristics

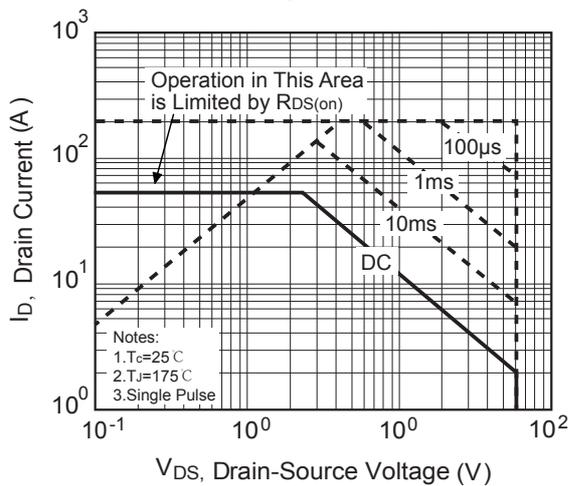


Gate Charge Characteristics

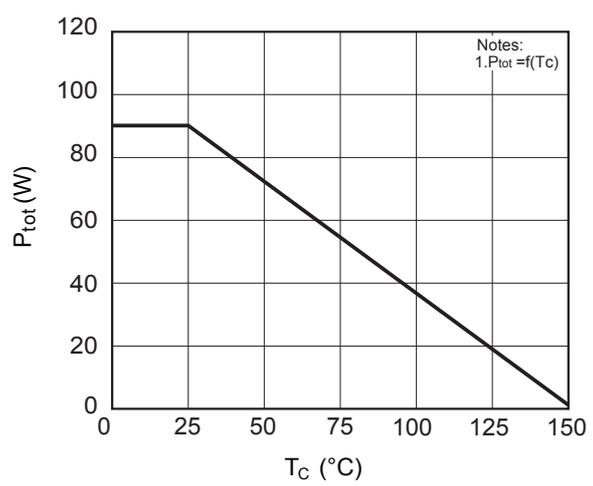
Typical Characteristics



Breakdown Voltage Variation vs. Temperature

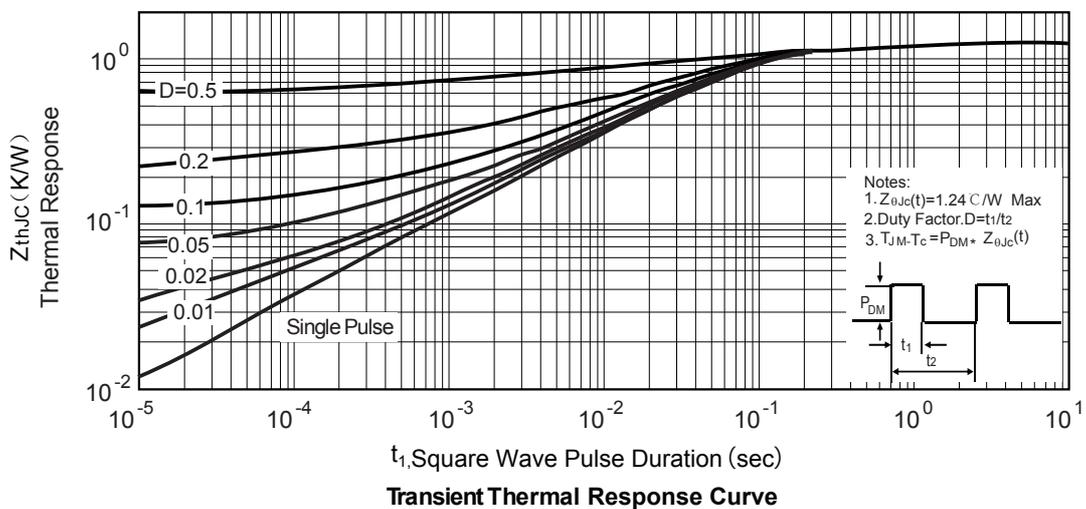


On-Resistance Variation vs. Temperature



Maximum Safe Operating Area

Power dissipation



Transient Thermal Response Curve